

ABSTRACT

Disclosed is a method for manufacturing an electronic device, the method including: placing an electronic component on a
5 substrate 11; forming standing portions 13 on the surface of the substrate 11 on which the electronic component 10 is placed, the standing portions 13 comprising a thermally decomposable resin; applying an encapsulating material 14 so as to encapsulate the electronic component 10 and cover around the standing portions 13
10 while exposing a portion of each of the standing portions 13 from the surface of the encapsulating material 14; heating the standing portions 13 to decompose and remove the standing portions 13, thereby forming holes 141 through the encapsulating material 14; and placing a conductive material 15 in the holes 141.